

AMENDMENTS TO THE ABSTRACT

Please substitute the following paragraph(s) for the abstract now appearing in the currently filed specification:

-- A semiconductor light-emitting element mounting member with an improved effective light reflectivity in a metal film serving as an electrode layer and/or a reflective layer, in which the metal layer has improved adhesion to a substrate, mechanical strength, and reliability and superior light-emitting characteristics. The semiconductor light-emitting element mounting member (a submount) is made by forming on a substrate metal films formed from Ag, Al, or an alloy containing these metals. The particle diameter of the crystal grains of the metal films is no more than 0.5 μm and the center-line average roughness Ra of the surface is no more than 0.1 μm . In a semiconductor light-emitting device, a semiconductor light-emitting element is mounted in the submount. --

[illegible]